

PROCESSING METHOD

ABSTRACT

A surface to be polished of a workpiece is polished by a polishing surface of a polishing pad by keeping a point on an outer circumferential edge of the surface to be polished at predetermined coordinates, i.e., first coordinates, included in a coordinate plane parallel to the polishing surface out of contact with the polishing surface and keeping a point on the outer circumferential edge of the surface to be polished at other coordinates, i.e., third coordinates, in the coordinate plane in contact with an outer circumferential edge of the polishing surface. In this manner, the surface to be polished of the workpiece is polished in its entirety, and a region of the polishing surface of the polishing pad in the vicinity of the outer circumferential edge thereof can be worn to the same degree as a region of the polishing surface that is located inwardly of the above region. The polishing surface of the polishing pad is thus prevented from developing a stepped profile due to the polishing of the surface to be polished of the workpiece. Even after the polishing pad has polished the workpiece, the polishing pad remains shaped for planarizing the surface to be polished of another workpiece.

[Fig. 6A]